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Integral Announces New Conductive Plastics Materials

CANTON, Mich., Oct. 20, 2014 /PRNewswire/ --Integral Technologies, Inc. (OTC-BB: ITKG) ("Integral"), an emerging light weighting leader and its wholly owned subsidiary, ElectriPlast Corp, announced the exciting development of two new materials. These materials keep Integral well in front of the industry performance curve. The focus of these new materials is the high performance shielding market and applications that will utilize ElectriPlast as a conductor. These new products will be protected by existing patents, with additional opportunities to add to Integral's IP portfolio from innovations achieved during product development.

The first material is a lightweight, high strength conductive material with an inner core of un-plated 12K and 24K carbon fiber, the second material is a highly conductive material using copper plated carbon fiber ("CuC"). Both materials can be formulated with most base resins, including ABS, PA66, PBT, PC, and PP. Technical information will be made available on the new materials in the next few weeks, at which time orders will be accepted for them.

"These new products are a continuation of our product portfolio expansion to meet our customers' growing needs," stated Mo Zeidan, ElectriPlast's Chief Technology Officer. "Selecting the right ElectriPlast pellet is critical in creating a solution for a successful application and these two new products provide additional options." The unplated carbon fiber pellet is a lower cost solution for applications requiring lightweight, EMI shielding, specifically consumer electronics products where shielding is critical, but also require strong, lightweight materials for mobility purposes. Depending on the loading of the carbon fiber to resin, attenuation ranged from 30dB at 30Mhz to nearly 55dB at 3 Ghz with wall thickness between 1mm to 3mm. Higher loading of carbon fiber will increase the shielding effectiveness. "For those applications where cost is a major driver, including consumer electronics, this product is the perfect mix of performance and price," stated Zeidan.

Increased requirements for light weighting and resistance to harsh environments have created an opportunity for highly conductive polymers to replace metal conductors in future applications. "Polymers capable of carrying high current with low ROA did not exist and our focus has been on creating material formulations, product processes and product interfaces to enable functional electric heaters, highly conductive traces and grounding planes," stated Slobodan ("Bob") Pavlovic, Vice President Engineering for ElectriPlast. "Different formulations were tested with continuous current ranging from 1A to 100A resulting in product temperatures well below heat deflection temperatures of selected polymers. We see great opportunities for this product line in the area of integrated heaters, ground planes, 3D PCB's, and integrated antennas. In parallel with material development, our applications engineering team is developing design solutions, making and testing prototypes to prove the technology and create product design to meet customer specifications."

About Integral Technologies, Inc.

(ITKG) ("Integral"), and wholly owned subsidiary ElectriPlast Corp, engage in the discovery, development, and commercialization of electrically conductive hybrid plastics used primarily as raw materials in the production of industrial, commercial and consumer products and services worldwide. Its core material, ElectriPlast®, is a non-corrosive, electrically conductive resin-based material whose properties allow it to be molded into any of the infinite shapes and sizes associated with plastics, rubbers and other polymers while reducing component weight by 40 to 60%. Integral is a leader in conductive hybrid plastics with a broad Intellectual Property portfolio referencing its ElectriPlast technology. Applications for ElectriPlast include: Shielding Wire, Power Electronics, Connectors, and Cables; Shielding, Conduction, Batteries, Semiconductors, Heated Elements, Sensors, Antennas, Medical Devices, Consumer Electronics and Acoustics, Fuses, Capacitors, Resistors, RFID, Bus bars and Terminals.

Safe Harbor Statement

This press release contains "forward-looking statements" within the meaning of Section 27A of the 1933 Securities Act and Section 21E of the 1934 Securities Exchange Act. These statements include, without limitation, predictions and guidance relating to the company's future financial performance and the research, development and commercialization of its technologies. In some cases, you can identify forward-looking statements by terminology such as, "may," "should," "expects," "plans," "anticipates," "believes," "estimates," "predicts," "potential," "continue," or the negative of these terms or other comparable terminology. These forward-looking statements are based on management's current expectations, but they involve a number of risks and uncertainties. Actual results and the timing of events could differ materially from those anticipated in the forward-looking statements, as the result of such factors, risks and uncertainties as (1) competition in the markets for the products and services sold by the company, (2) the ability of the company to execute its plans, (3) other factors detailed in the company's public filings with the SEC, including, without limitation, those described in the Company's annual report on Form 10-K for the year ended June 30, 2014 as filed with the Securities and Exchange Commission and available at www.sec.gov, and (4) the parties may be unable to agree upon definitive agreements. You are urged to consider these factors carefully in evaluating the forward-looking statements.

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